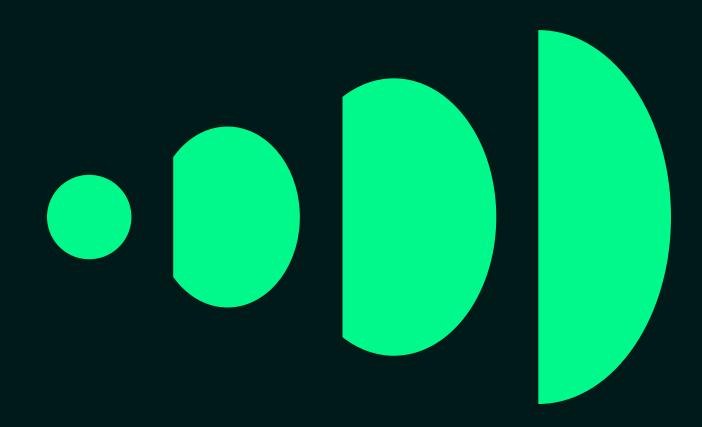


ISES MEMBERSHIP BENEFITS

BE PART OF THE WORLDS LEADING SEMICONDUCTOR ASSOCIATION DEDICATED EXCLUSIVELY TO END USERS, FOUNDRIES, IC DESIGN, IDM'S, OSATS & RESEARCH INSTITUTE LEADERS





INFO@ISESGLOBAL.COM







ABOUT US

ISES Mission

The International Semiconductor Executive Summits (ISES) is where leaders connect with the end goal to collaborate and share ideas in a trusted network to establish an effective global semiconductor ecosystem. We provide a unique platform which entails collaboration through global leading executives connecting with peers, partners, and customers to connect ideas share best practices, identify challenges and gain visibility across the global semiconductor industry.



Leadership

ISES is led by an Advisory Board and a set of subsidiary **Task Forces**. These Advisory Board of Directors consist of semiconductor industry executives from acclaimed companies including **Intel**, **TSMC**, **Broadcom**, **MediaTek**, **Infineon**, **Vanguard**, **Ams Osram**, **Amkor** and many other global leaders who collaborate to support our mission.

Global Executive Network

ISES hosts the highest NPS rating Semiconductor Summits in the World. With a capped audience of 150 leaders in each major region: USA, Europe, Taiwan & China consisting of Participation of Leaders in **Technology, Manufacturing, Operations and R&D.**

Visibility, Intelligence & Events

With absolute leverage of the above, ISES provides its members a platform for collaboration and strategic thought leadership through our hybrid regional and global events, dedicated to Advanced Packaging, Memory Manufacturing, Automotive Semiconductors, Power Semiconductors, Market Research and more. Covering strategic technical discussion alongside a commitment to Inclusion & Diversity & Workforce Development initiatives, & a variety of marketing communications and visibility opportunities.



• ISES Advisory Board Members







HAMID AZIMI Corporate VP, Director of Substrate Packaging TD

intel



MARKUS KEIL VP Global Operations and Member of Executive Board





SUNIL BANWARI VP Business Development, Advantest Cloud Solutions

ADVANTEST



VINCENT DICAPRIO

VP Advanced Packaging and ICAPS / Head of Business and Corporate Development



JENNIFER ZHAO

GM & EVP for Advanced Optical Sensors Division



CJ HSIEH

COO

ASPEED



XIAOXIN QIU

CEO

vxesa



MARTIN WEIGERT

VP & GM Industrial Fiber Products Division

BROADCOM*



YUANYUAN ZHOU

Global Business Director



CMO



OINGCHUN ZHANG

Professor





ANDY CHUANG

VP Business Development





FARHAT JAHANGIR CEO and Co-Founder

GS臺 ELECTRONICS



VANCE WANG Formerly VP New Fab Project at GTA



CHANG FU Advanced Module R&D Dep., Deputy Director





SHIH-CHIEH CHANG General Director, Electronic and Optoelectronic System





YAOJIAN LIN VP, GM of Technology R&D Center

JCET



IAN HSU Director IC Packaging Technology Development



RYAN CHEN General Manager of Computing and AI

Technology Group



AKSHAY SINGH VP, Advanced Packaging Technology Development

Micron



JY ZHANG Chairman & CEO





VP Product Test Engineering

Qualcomm





Senior Adviser to President

REALTEK



SHU-MING LIU



LUBA TANG Founder & CEO



TIM YEH Technical Director of Power BU





Research Laborations

JOSEPH CHOU

SEMITO?



YONGXIANG WEN Process Technology

Silan 士兰微电子



YU-PO WANG

VP Corporate R&D

Center



ANDREW PENG Formerly VP BD Greater China at Spin

Memory



KEY CHUNG

7-1-通客敬電

Advanced Packagin CTO



YC LEE CEO





Director, Manufacturing Technology Center



SHAOJUN WEI Professor (はまえま Display University



R&D Director VIS V











WEIHUA CHENG COO

长江存储 YANGTZE MEMORY



SANTOSH KUMAR Director & Principal Analyst

Reliance
Industries Limited
Growth is Life



WEI LI Chairman

ZINGSEMI



Secretary General of China Integrated Circuit Innovation Alliance
Academician of the International Eurasian Academy of Sciences President of IC branch of China Semiconductor 中国科学院做世子研究所

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• ISES Power Advisory Board Members





RALF BORNEFELD

SVP, Power Semiconductors & Modules



BOSCH



ALEX LIDOW

CEO





JIM WITHAM

CEO





RAINER KAESMAIER

Managing Director, Semiconductors





DENIS MARCON

General Manager





MARCO GIANDALIA

VP IC Design





CARLOS CASTR

VP & GM Power GaN FETs

nexperia



AVINASH KASHYAP

VP Power Technology





EDOARDO MERLI

Executive Vice President, Power Transistor Sub-Group Automotive and Discrete Group





CHRISTOPHE MALEVILLE

CTO





PRIMIT PARIKH

Co-founder, President & COO

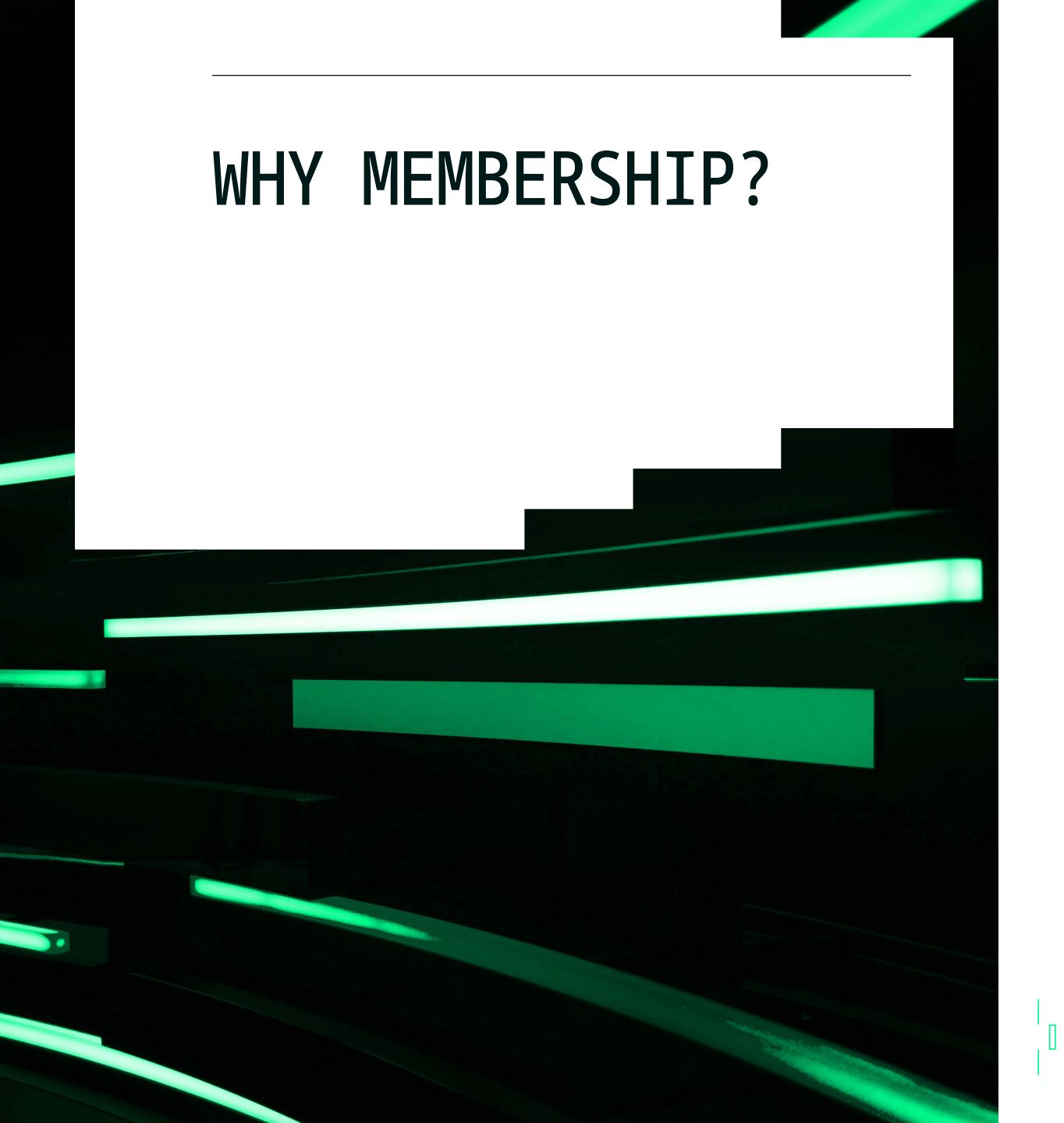
transphorm



AGNES JAHNKE

Product Marketing Manager SiC and GaN

xfab







Traditionally ISES has been funded through supplier sponsorship, allowing our IC Design, Foundry, IDM, End User & OSAT partners to attend free of charge. However, as we continue to grow as a platform by expanding to new regions such as Southeast Asia & the Middle East, whilst delivering the best-in-class speakers and venues we can no longer rely on supplier sponsorship alone.

Moreover, for us to continue to deliver and expand our events to you at this elite level, we will be introducing a low-cost Membership model for each IC Design, IDM, Foundry, End User, OSAT & Research Institution who wishes to participate at our events. The following pages will summarise the key benefits and pricing of the membership package for your company.



Reports

1 · YEAR ROUND ACESS TO ALL ISES 2023 PRESENTATIONS & VIDEO RECORDINGS

ISES Members have access to technology presentations, market reports and our exclusive, specially curated, ISES Presentations and Market Updates as of their membership benefits. All of these Presentations and Market Updates provide information that can be used for corporate strategy, new product development, innovation, research, technology development or marketing. ISES Staff is glad to assist you access all information.









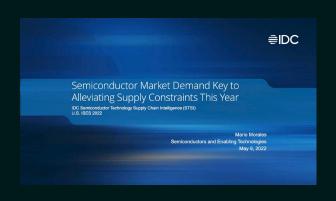










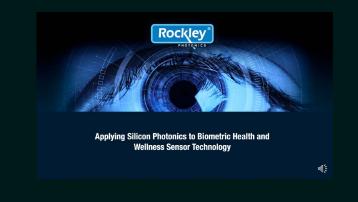










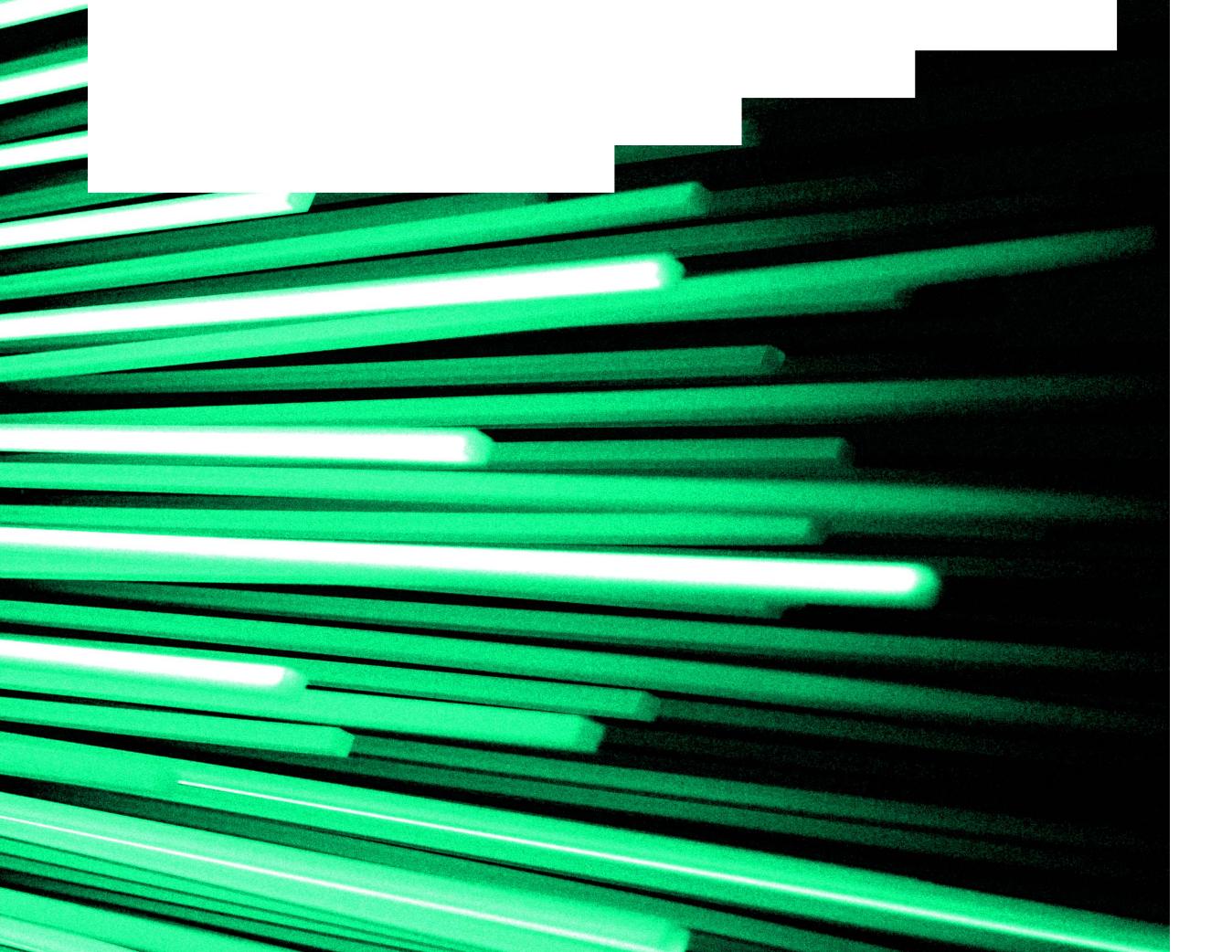








² · ACCESS TO THE GLOBAL ISES NETWORK







Events

ISES strengthens the connections among its members through our Executive Summits. Designed to meet & discuss challenges and opportunities, and to explore collaboration possibilities. ISES events are by-invitation-only to ensure a relevant audience and highly selective to ensure effective networking. Upon registering our ISES annual Membership, your company will gain market intelligence, brand visibility and discounted member rate I person access to the following ISES 2023 events:

ISES Middle East	22-23	February	Oman
ISES USA	07-08	March	USA
ISES Taiwan	09-10	May	Taiwan
ISES EU Power	14-15	September	Italy
ISES China	17-18	October	China
ISES SEA	14	November	Malaysia

View upcoming events on: www.isesglobal.com_





3 · PROMOTION & VISIBILITY FOR YOUR COMPANY

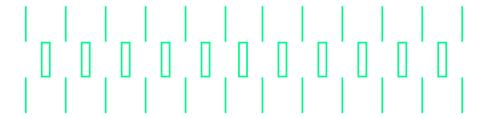




Promotion

ISES is proud to promote its members. We offer a wide range of services to create more visibility for your company

- Member Product Release via our Mailing List of 10,000+ subscribers
- Media Visibility We will include your company logo In all general ISES flyer promotions to our 21,000+ followers on LinkedIn Community, plus our event website. We will also include your company logo an 'about us and company contact info In all ISES event digital program brochure to be accessed on our event apps.
- Member Video Interviews: We will give your In-person event representative the chance to deliver a testimonial with digital logo placement as part of our event video trailers which will be released via mail blast and LinkedIn post after each event.
- Member News Send us your news and we will share your innovations with our network through social media.
- Sponsorship & Event Participation Opportunities We offer a special 10% discount on sponsorship packages as an exclusive benefit to our members to increase your company's visibility at our activities and events



3 · PROMOTION & VISIBILITY FOR YOUR COMPANY

REGIONS COVERED

USA
Taiwan
Europe
Middle East
China



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TOPICS COVERED

ISES USA/TAIWAN/CHINA

- Advanced Packaging
- Al
- Chiplets
- High Performance Computers (HPC)
- Memory Manufacturing
- Supply Chain
- 5G/6G

POWER SEMICONDUCTOR

- Automotive
- GaN
- SiC
- Supply Chain
- Renewable Energy

ISES OMAN

- Design Verification
- MEMS & Sensors
- Power Semi

ISES SEA

- Advanced Packaging
- Assembly & Test
- Supply Chain



MEMBERSHIP

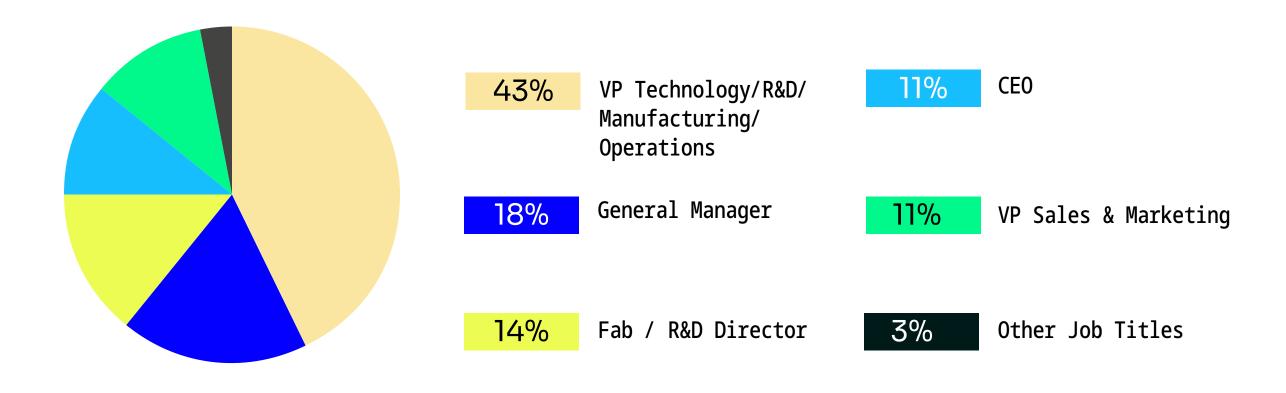
Promotion

FACTS & FIGURES

778	Attendees
150	Thought Leaders Presentations
72+	Hours of Networking
360	Business Meetings Pre-Arranged
21,000+	Follower on LinkedIn
132	IDM/Foundry (Fabs) Companies in Attendance
29	OSAT Companies in Attendance
157	Fabless Companies in Attendance
61	End User Companies (Automotive/Mobile Phone/Data Servers and etc) in Attendance
62	Equipment & Materials Manufacturing Companies in Attendance

3 · PROMOTION & VISIBILITY FOR YOUR COMPANY

JOB TITLE BREAKDOWN





MEMBERSHIP

Promotion

11

COMPANY PROFILES

IC Design Houses

IDMs

Foundries

Research Institutes

OSATs

Semiconductor Equipment & Materials Manufacturers

End User: Automotive, Communications, computing, healthcare, transportation, clean energy, and others)

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4 · BECOME A MEMBER

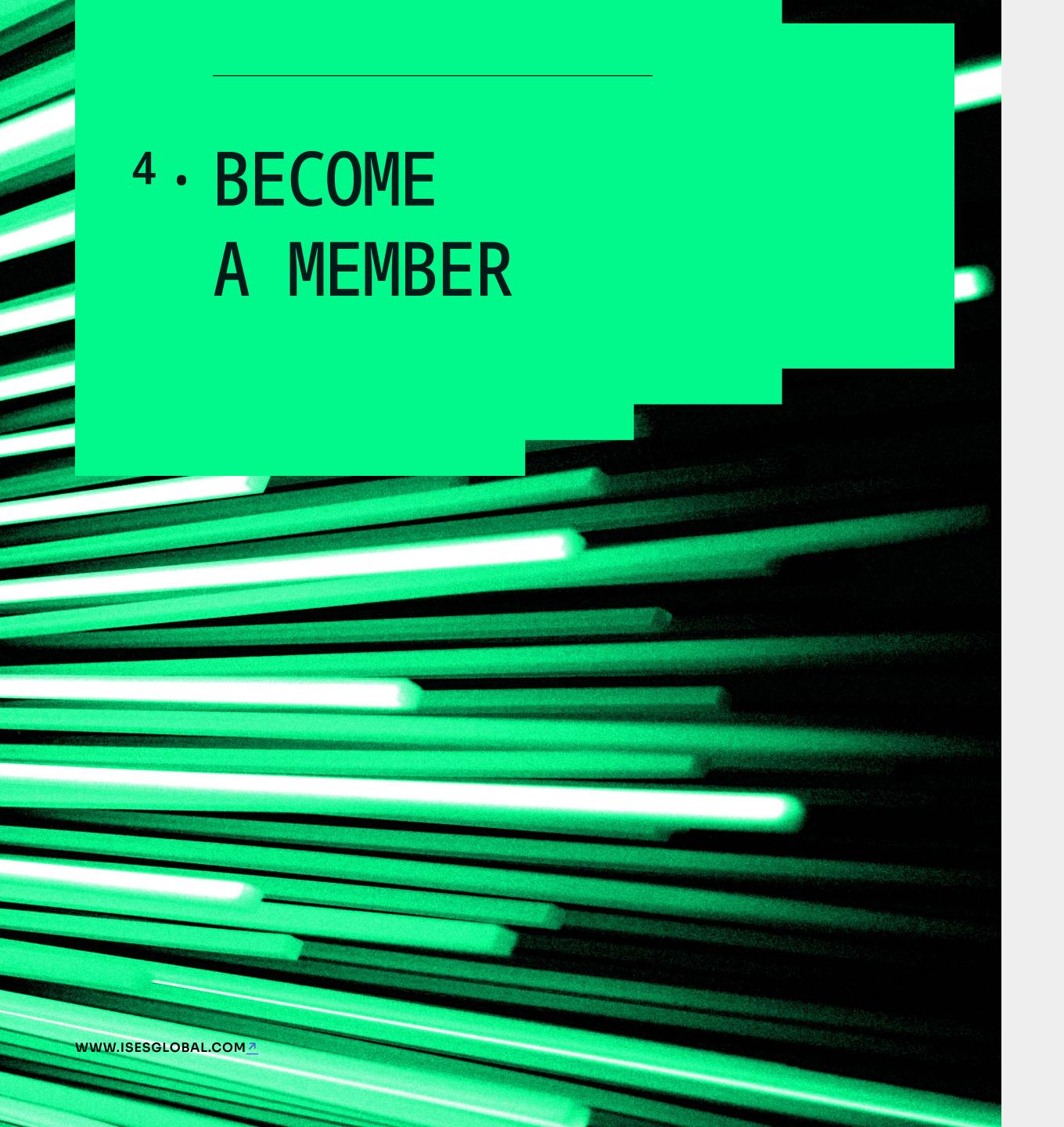


Each of our End User, IC Design, IDM, Foundry, OSAT & Research Institute partners will be allowed to register one annual membership package for the year, which will include 1 VIP attendee pass to ALL ISES 2023 events for C/GM/VP & Director leadership executives.

This will be in addition to the following benefits below:

MEMBER BENEFITS SUMMARY

- All additional event passes will be registered at the lower member rate (please see example on next page)
- First refusal to available speaker slots (subject to Advisory Board approval)
- Access to all ISES members portal which includes exclusive access to all event presentation slides & video recordings
- Full year's Membership company logo branding in association with ISES on online and offline materials
- You will also receive priority consideration to join the Advisory Board &/OR Event Task Force positions





MEMBERSHIP

Member

JOIN TODAY

EXCLUSIVE RATE FOR LOCAL CHINA

\$3,000

*Below is an example of membership cost savings when registering an ISES event pass:

Member Rate per event: \$1,197

Non-Member rate per event: \$2,497

Please click here to register online:

WWW.ISESGLOBAL.COM/MEMBERSHIP/

ISES MIDDLE EAST 2023

DATE 22-23 February

LOCATION Oman

ISES USA 2023

O7-08 March

LOCATION Phoenix, Arizona

ISES TAIWAN 2023

OP-10 May 2023

LOCATION Taipei

ISES EU POWER 2023

DATE 14-15 September

LOCATION Italy

ISES CHINA 2023

DATE 17-18 October

LOCATION China

ISES SEA 2023

DATE
14 November

LOCATION Singapore/Malaysia

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